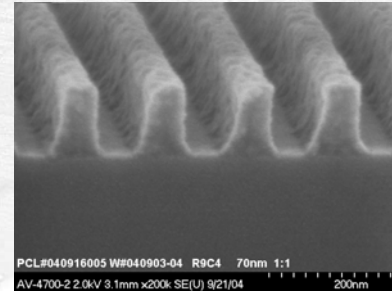
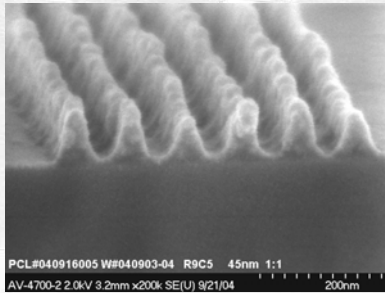


Line Edge Roughness Workshop

Resist Limitations Workshop

February 27, 2005



Karen Turnquest
Kim Dean



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Introduction

➤ Objective:

- To understand the current status of resist limitations research in the industry
- To better understand what knowledge is lacking

➤ Expected outcome:

- Spawn new ideas that will lead to future projects and activities for both SEMATECH and the industry

Structured Brainstorming

The best way to get good ideas is to have lots of ideas.

- What are specific resist limitation issues that need to be addressed?
- Prioritize the top 3 issues, then answer the following:
 - Are they wavelength dependent? If so, what wavelength(s)?
 - Are they node dependent? If so, what node(s)?
 - Who should play a major role in this research effort (consortia, universities, national laboratories, IC manufacturers, resist or tool vendors)?
 - What is the anticipated outcome?
 - When do we need the answer?

Structured Brainstorming

The best way to get good ideas is to have lots of ideas.

Divide into 4 groups:

1. Resist/tool suppliers

Facilitator: Karen Turnquest

2. IC Manufacturers

Facilitator: Jan Makos-Brotherton

3. Consortia/researchers/universities/government labs

Facilitator: Beth Kells

4. Variety group

Facilitator: Jeff Meute



Breakout summary presentation template

Variety Group - LER

Group Variety



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Specific LER Issues (I)

1. Metrology standards
2. Device impact
3. Integration/ post resist processing
4. Variability/ process control
5. Funding

Specific LER Issues (II)

6. Develop/ dissolution
7. Material limits
8. Modeling standards/ integration
9. Aerial image/ contrast

Top Issue#1

Metrology (standards)

- Wavelength: Independent
- Node: Yes, frequency/ measurement
- Who: IC makers, NIST, CDSEM eqpmt
- Anticipated outcome: Well developed standard
- When: asap

Top Issues #2

Device impact

Problem now? LER frequency range? Value?

- Wavelength: Independent
- Node: Yes
- Who: Device makers, designers, suppliers
- Anticipated outcome: Value, Measure, Yield vs LER (freq), Device type
- When: ASAP

Top Issues #3

Integration

Post processing, substrate, etch, multi layer processing,

- Wavelength: Dependent
- Node: Yes
- Who: Device makers, suppliers
- Anticipated outcome: new processes
- When: ASAP

Breakout summary

Resist Limitations

**Folks from variety of
areas**



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Specific Resist limitation Issues (I)

1. Resist design
2. New imaging scheme
3. Pattern collapse
4. Simulation
5. Economic values/implementation time
6. Environmental
7. Metrology

#1 Issues

Topic: Design of resist

1. Control of diffusion of small molecules in resist films
2. Molecular designs
3. Homogeneity
4. Photochemistry

Wavelength dependent: Yes

Node dependent: Yes

Who: Universities, consortium, Resist manufactures

Anticipated outcome: Identify new design concepts and tools for accelerating resist development

When: ASAP

#2 Issues

Topic: New imaging scheme

1. Multi-layer scheme, top surface imaging
2. New devise scheme
3. Self assembly/pixel level molecular imaging

Wavelength dependent: Yes

Node dependent: Yes

Who: Universities, consortium, Resist manufactures , Device manufacturers

Anticipated outcome: Identify and demonstrate most attractive new imaging schemes

When:ASAP



#3 Issues

Topic: Pattern collapse

1. Resist modulus
2. Substrate effect
3. Capillary actions, rinsing solutions
4. Rigorous simulation

Wavelength dependent: No

Node dependent: Yes

Who: Universities, consortium, Resist manufactures , Device manufacturers

Anticipated outcome: Reduce pattern collapse and improve aspect ratio capability

When:ASAP



What's Next?

- Results will be compiled and distributed in the next two weeks
- These results will help give direction to SEMATECH and the industry